



Hewlett Packard
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DWDM Silicon Photonics: From PDK to 3D-Integrated SiPh Receiver Design

Jinsung Youn, Hewlett Packard Labs

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Outline

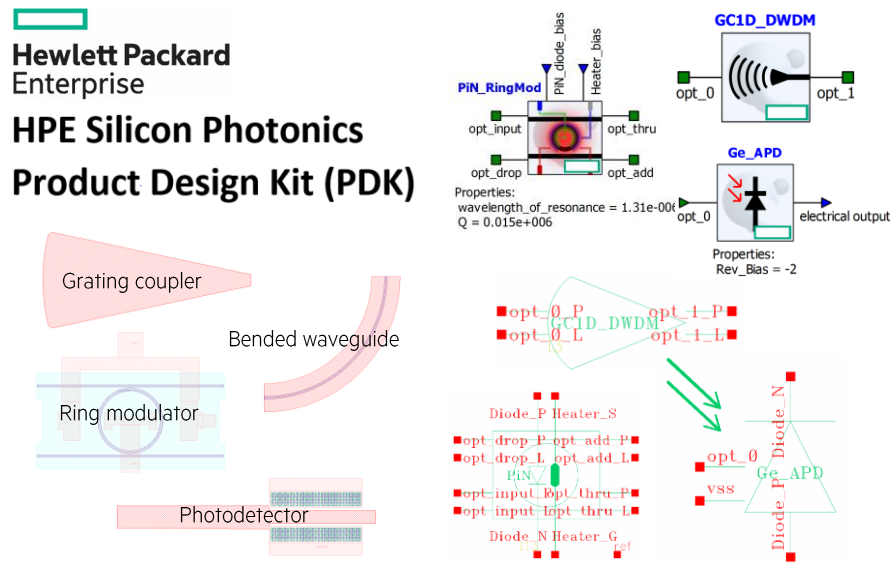
- **HPE Silicon Photonics (SiPh) Research**
- **HPE SiPh PDK**
 - One example: Photodetector behavioral model for receiver design
- **3D-Integrated DWDM Receiver Design**
- **Summary**



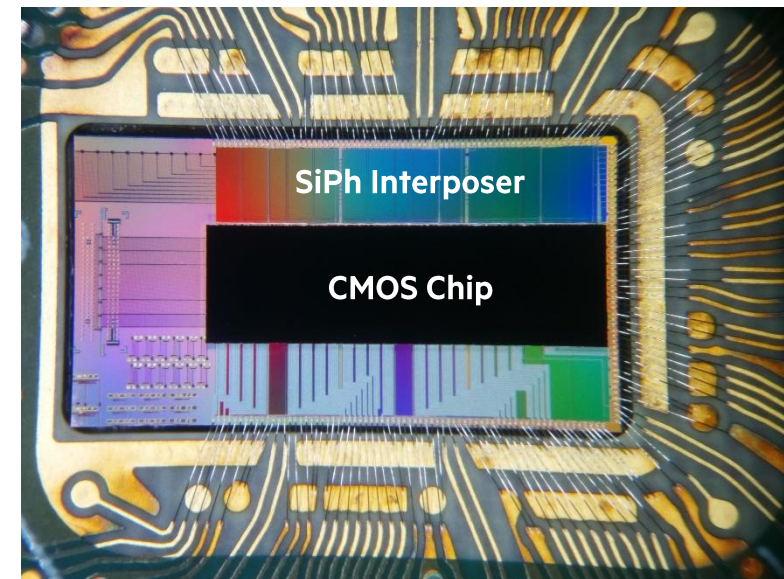
HPE SILICON PHOTONICS RESEARCH

- **Silicon Photonics PDK development**
 - To lower the entry barriers for Silicon Photonic design
- **3D-integrated DWDM SiPh transceiver design**
 - Microring-based optical link to achieve high aggregate bandwidth in a small form factor

SiPh PDK development



DWDM SiPh design



PROCESS DESIGN KIT

- **What is a PDK?**

- PDK is a set of files used within the semiconductor industry to model a fabrication process **for the design tools** used to design an integrated circuit. The designers use the PDK **to design, simulate, draw and verify the design** before handling the design back to the foundry to produce chips. The data in the PDK is specific to the foundry's **process variation** and is chosen early in the design process. An **accurate PDK** will increase the chances of first-pass successful silicon (Source: *Wikipedia*)

- **Key requirements**

- Accurate simulation models
- Compatibility with EDA tools
- User-friendly interfaces
- Statistical parameters



HPE'S SILICON PHOTONICS PDK

- **Schematic symbols and layouts**

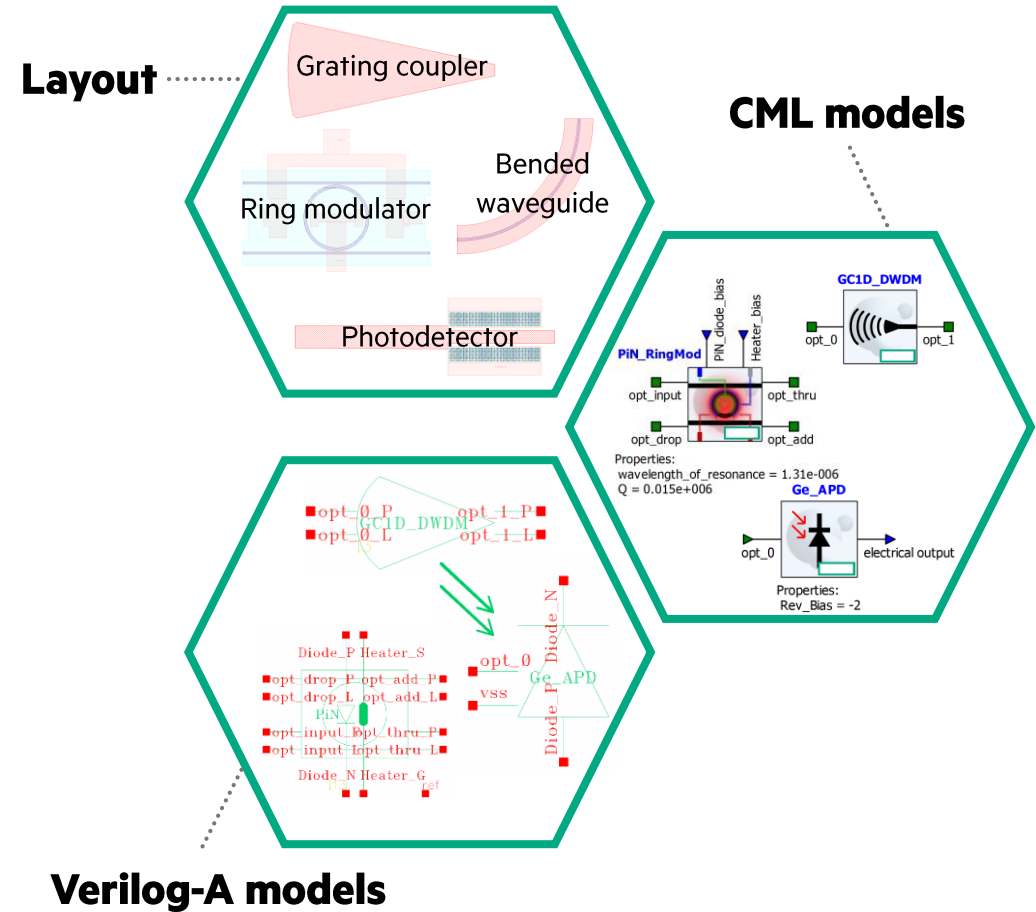
- Grating couplers
- Passive devices
 - Waveguides, tapers, splitters ...
- Active devices
 - Modulators, photodetectors, phase shifters
- Packaging devices
 - TSV, microbump, high-speed metal pads

- **Behavioral models**

- Verilog-A models for co-simulation with electronic circuits
- CML models for system-level simulation

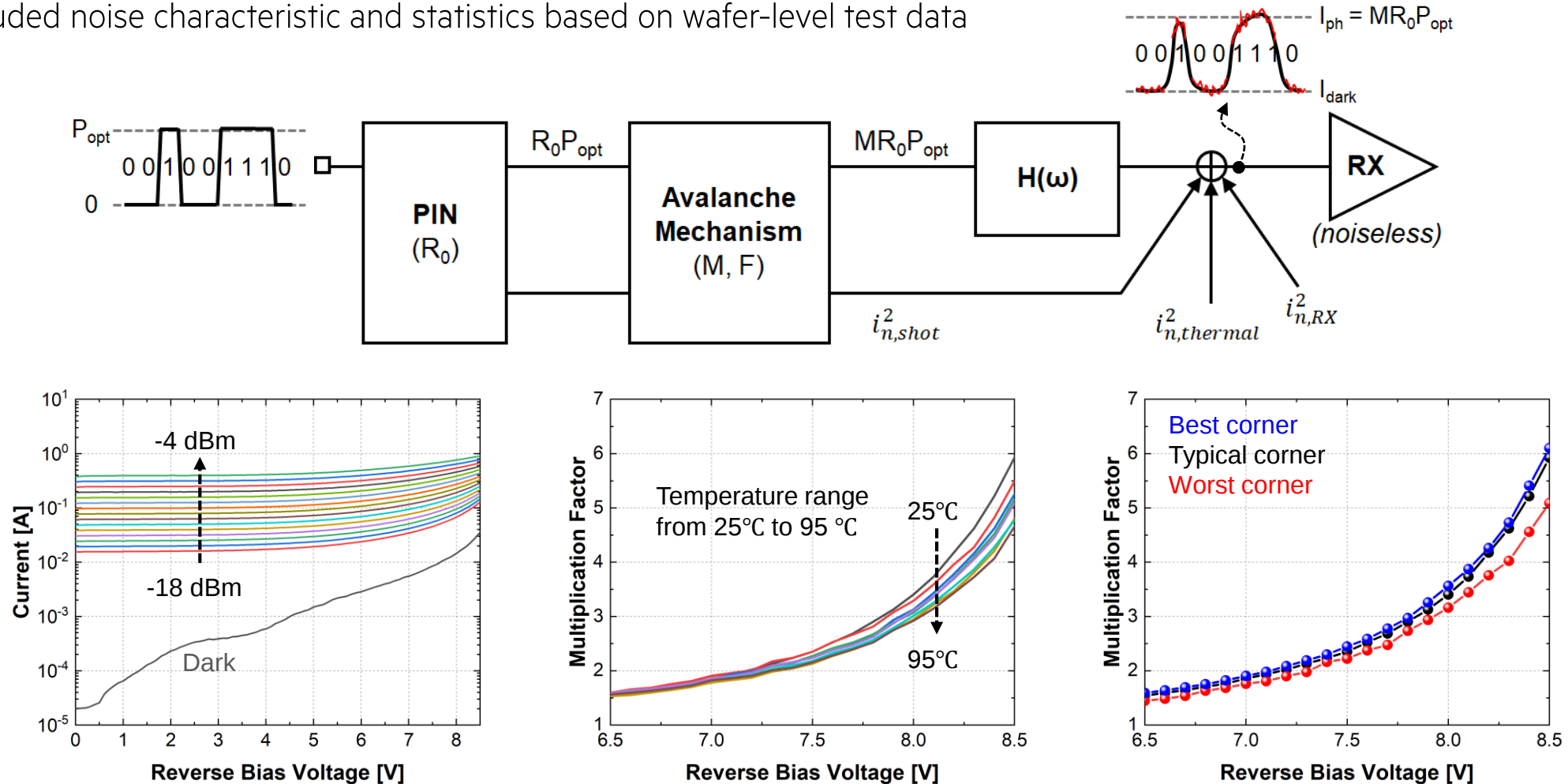
- **PDK manual**

- Device parameters and wafer-level test data
- Design guidelines



PHOTODETECTOR BEHAVIORAL MODELING

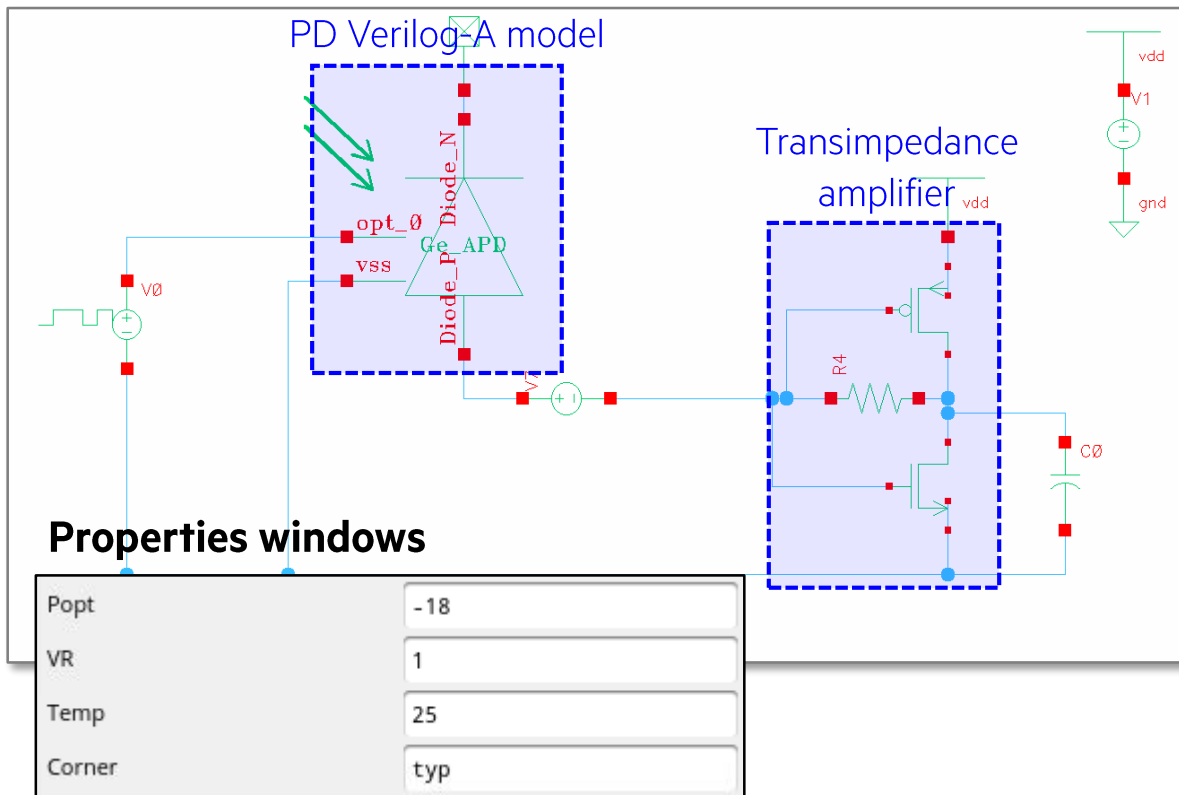
- **Accurate PD behavioral model over a wide range of bias voltages**
 - Included noise characteristic and statistics based on wafer-level test data



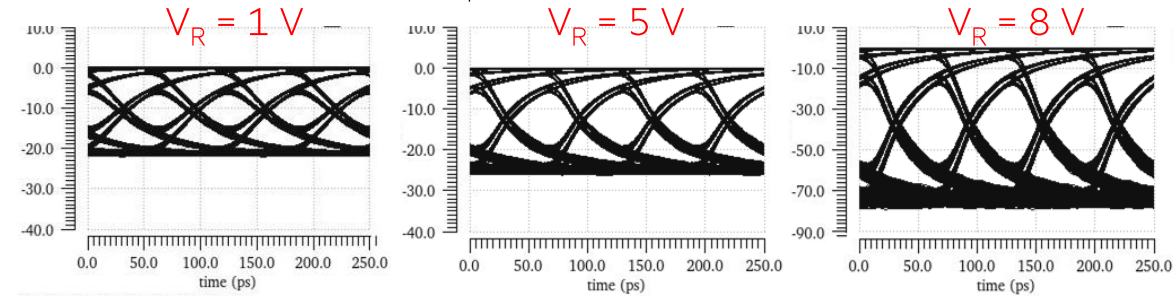
PHOTODETECTOR BEHAVIORAL MODELING (CONT'D)

- **User-friendly interface with Cadence Virtuoso**
 - Co-simulation with transistor-level electronic circuits

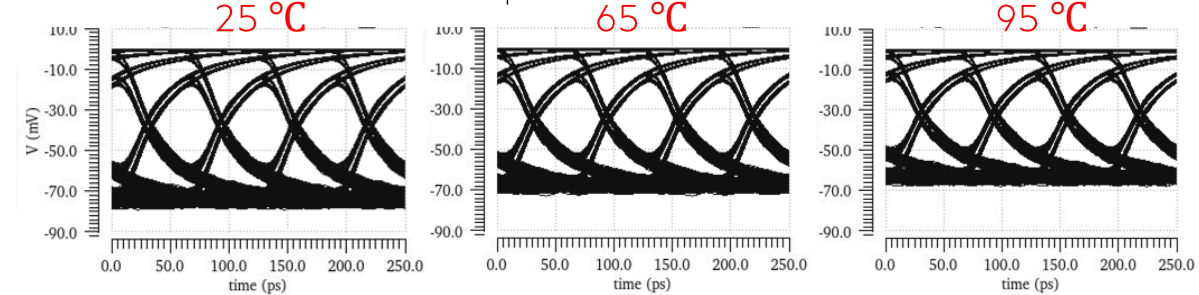
Cadence Virtuoso Schematic Editor



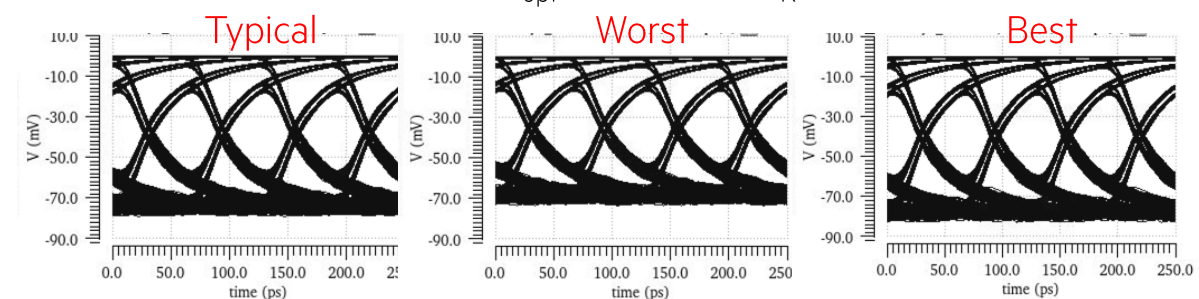
- **Bias voltage** sweep ($P_{opt} = -18$ dBm, 25°C , Typical)



- **Temperature** sweep ($P_{opt} = -18$ dBm, $V_R = 8$ V, Typical)

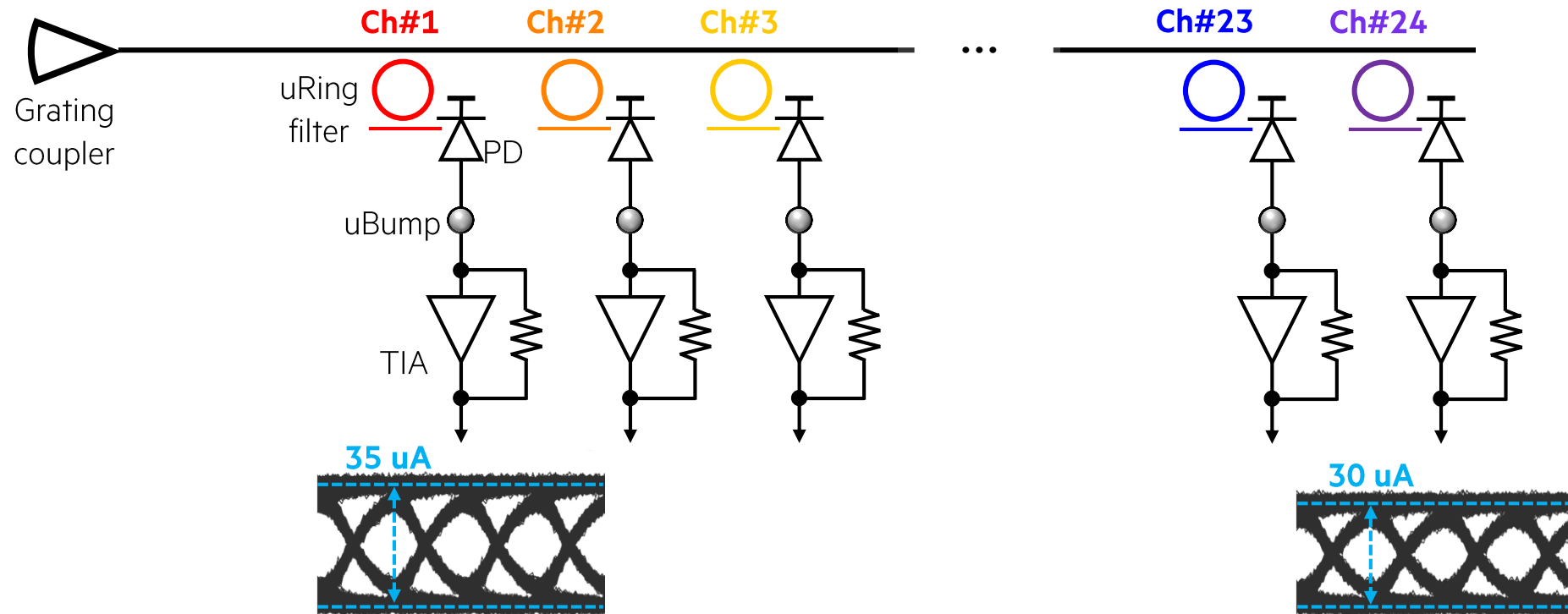


- **Process corner** sweep ($P_{opt} = -18$ dBm, $V_R = 8$ V, 25°C)



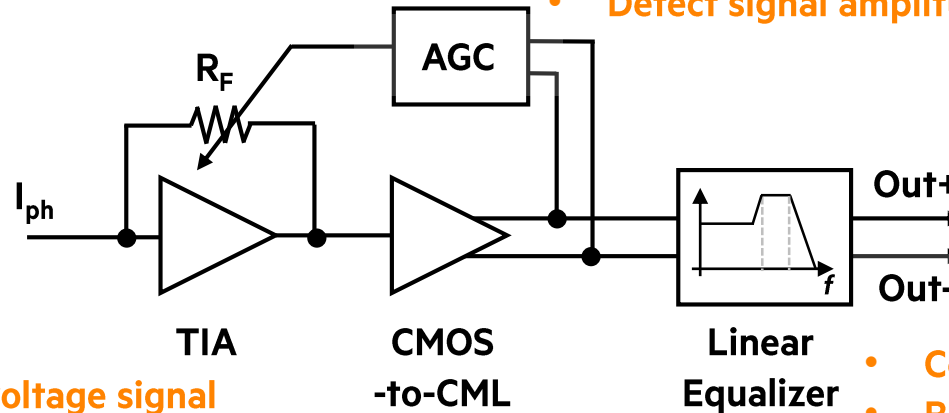
3D-INTEGRATED DWDM RECEIVER DESIGN

- **CMOS receiver chip is flip-chipped onto SiPh interposer**
 - CMOS receiver has 24 front-end channels operated at 16 Gb/s ($\approx$ aggregate bandwidth of 384 Gb/s)
 - SiPh interposer has a single grating coupler and a bus waveguide with 24 microrings and 24 photodetectors
- **Transient simulation with Verilog-A models from PDK**



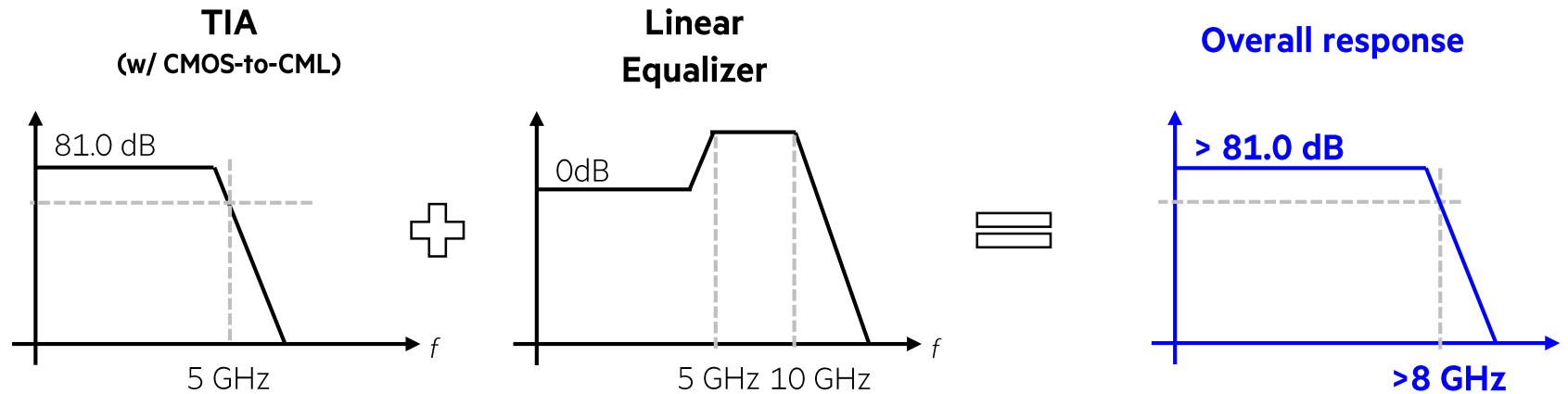
RECEIVER CIRCUIT DESIGN

- Wide input dynamic range
- Detect signal amplitude and control TIA gain



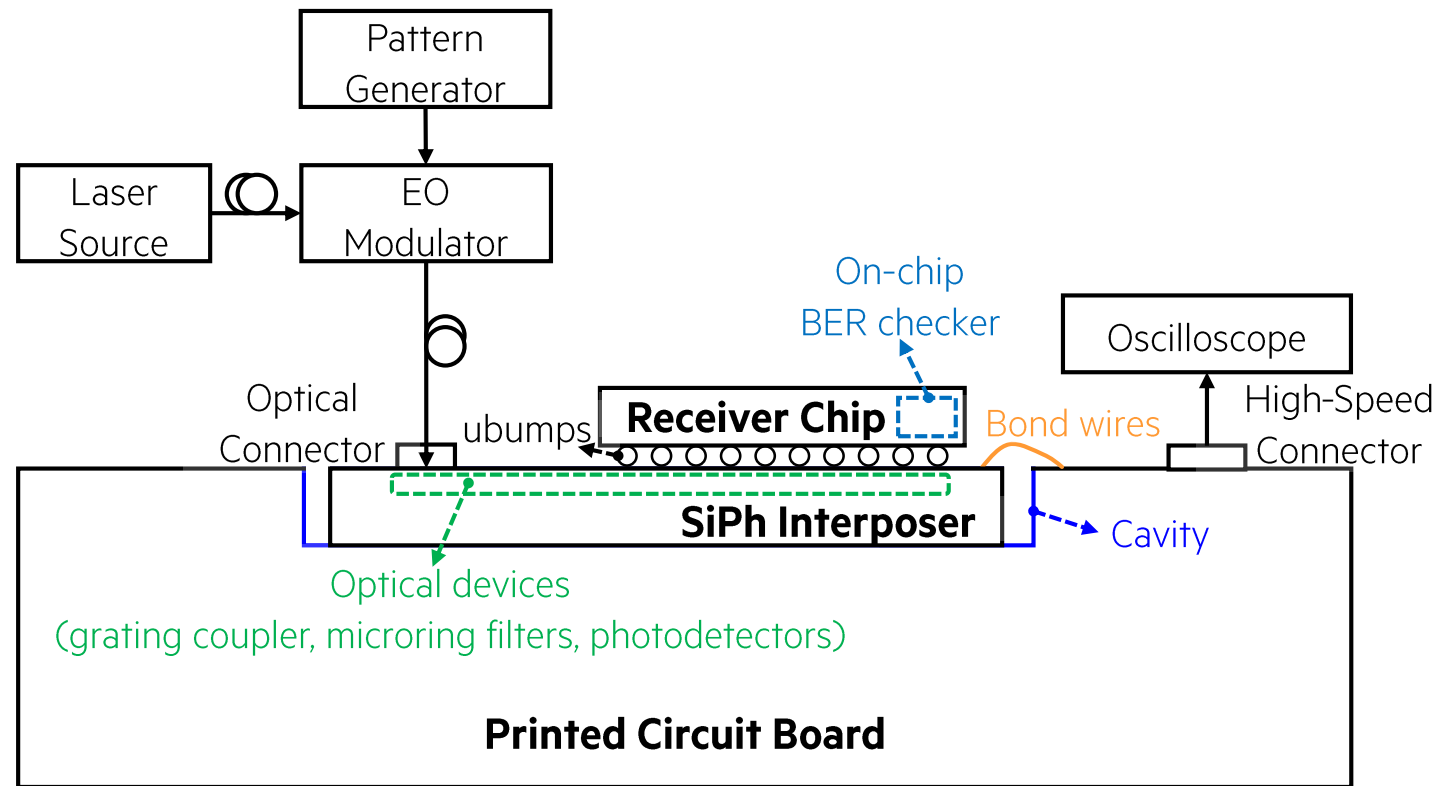
- Converts PD current to voltage signal
- High-gain and low-noise characteristics

- Compensate bandwidth limit due to TIA and packaging
- Boosting gain controllability to optimize bandwidth



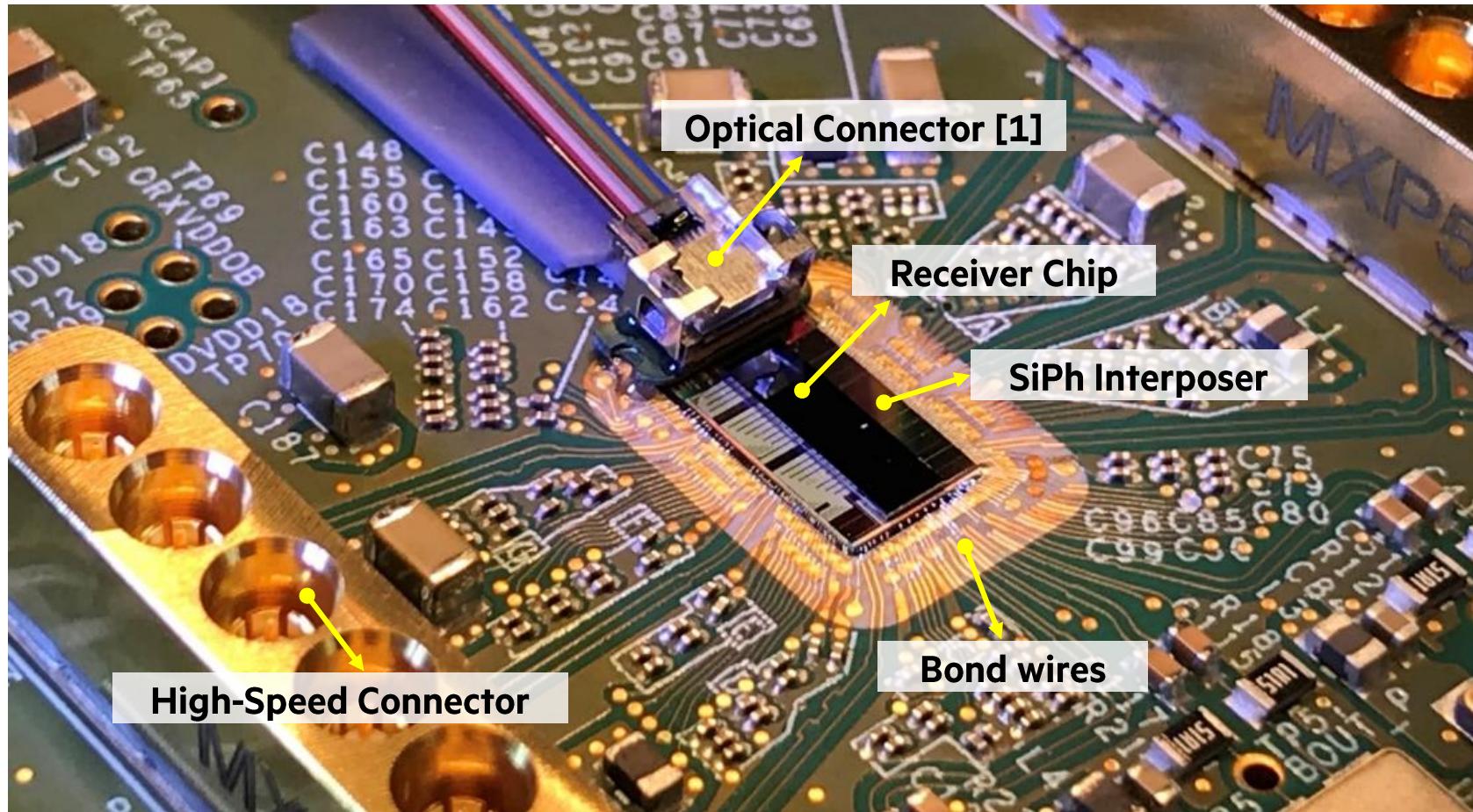
MEASUREMENT SETUP

- CMOS receiver chip is flip-chipped onto SiPh interposer
- 3D-integrated SiPh package is mounted and wirebonded to printed circuit board
- Power consumption: 384 mW with 1.2-V ($\approx$ Energy efficient of 1 pJ/bit)



MEASUREMENT SETUP (CONT'D)

- Picture of SiPh receiver mounted on the test board

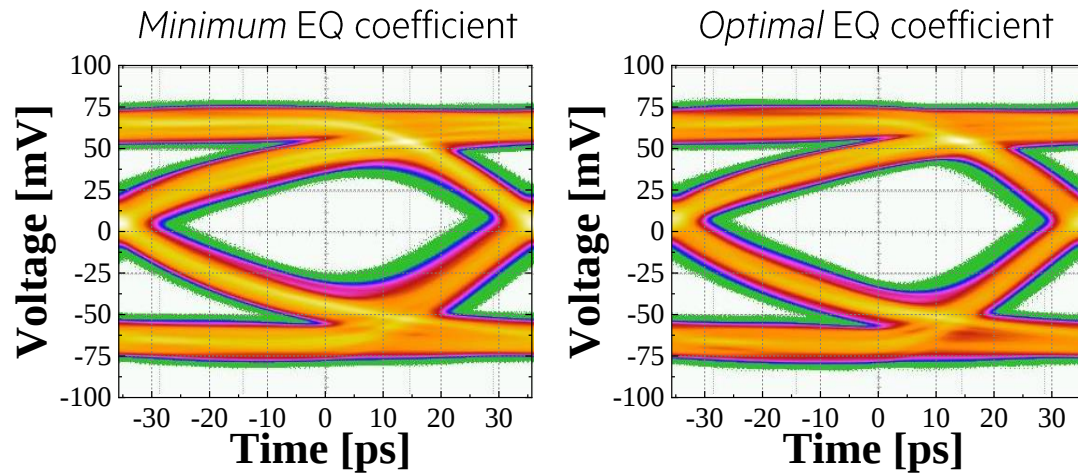


[1] S. Mathai, Optical Interconnects, 2020

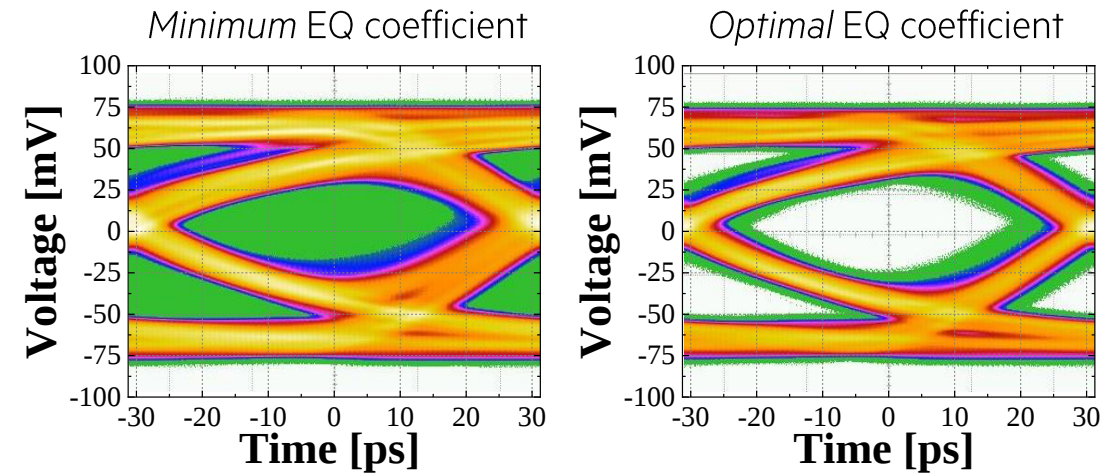
MEASUREMENT RESULTS

- Measured 14- and 16-Gb/s eye diagrams at the first channel ($\lambda = 1305.7$ nm)
- Clean eye diagrams with optimized equalizer coefficients
- BER < 10^{-12} measured with on-chip BER checker

14-Gb/s eye diagrams



16-Gb/s eye diagrams



SUMMARY

- **HPE's Silicon Photonics PDK**
- **3D-Integrated SiPh Receiver Design**
- **Demonstration of 16-Gb/s optical data transmission with error-free condition**
- **SI/PI/TI analysis of 3D-integrated SiPh system will be presented at DesignCon2021**



THANK YOU

www.labs.hpe.com

jin-sung.youn@hpe.com

- **Hewlett Packard Labs' R&D interests in EU: Photonics, AI & quantum computing**
- **Looking for consortium partners and EU funding opportunities!**
Thomas.Van-Vaerenbergh@hpe.com
- **Upcoming special issue: APL photonics – Photonics and AI in IT, deadline July 9**